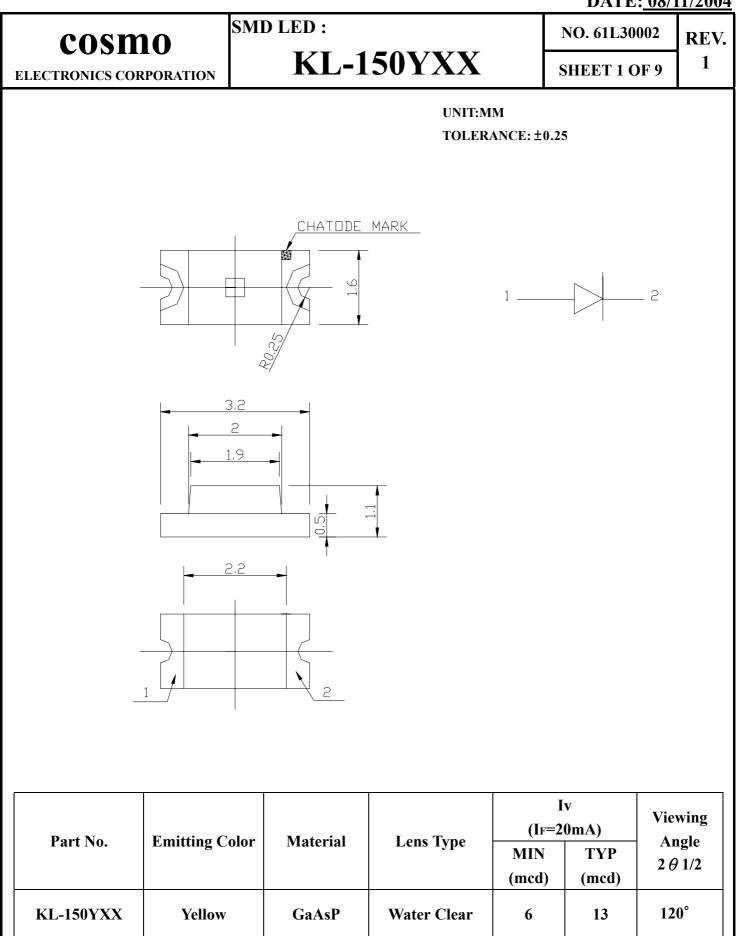
DATE: 08/11/2004



DATE: 08/11/2004

cosmo

SMD LED :

# KL-150YXX

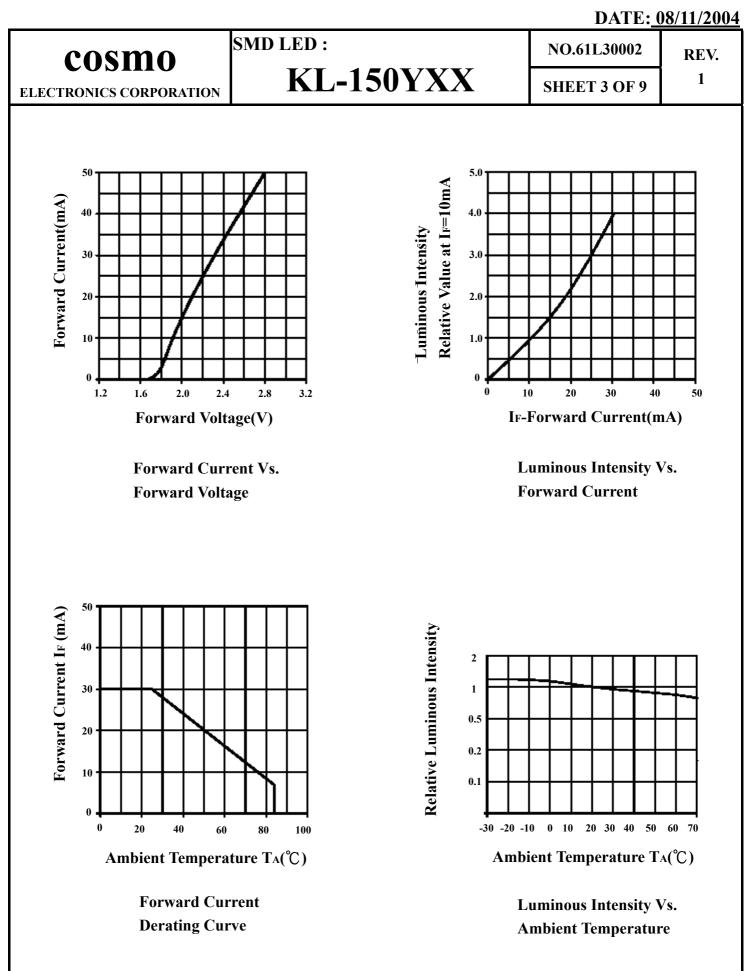
 NO. 61L30002
 REV.

 SHEET 2 OF 9
 1

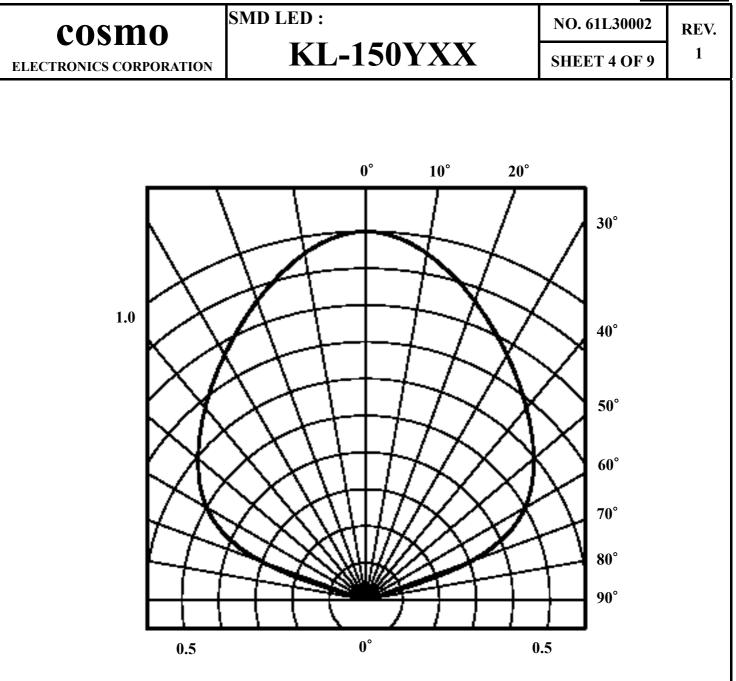
**ELECTRONICS CORPORATION** 

Absolute maximum ratings (TA=25°C)		Y Yellow (GaAsP)	Unit
Reverse voltage	VR	5	V
Forward current	IF	30	mA
Forward current(Peak)	IFP	100	mA
1/10 Duty Cycle,0.1ms Pulse Width			
Power dissipation	Pd	50	mW
LED LAMPS:			
Operating temperature	Тор	-40~+85	°C
Storage temperature	Тят	-40~+85	°C
LED DISPLAYS:			
Operating temperature	ТА	-40~+85	°C
Storage temperature	Tstg	-40~+85	°C

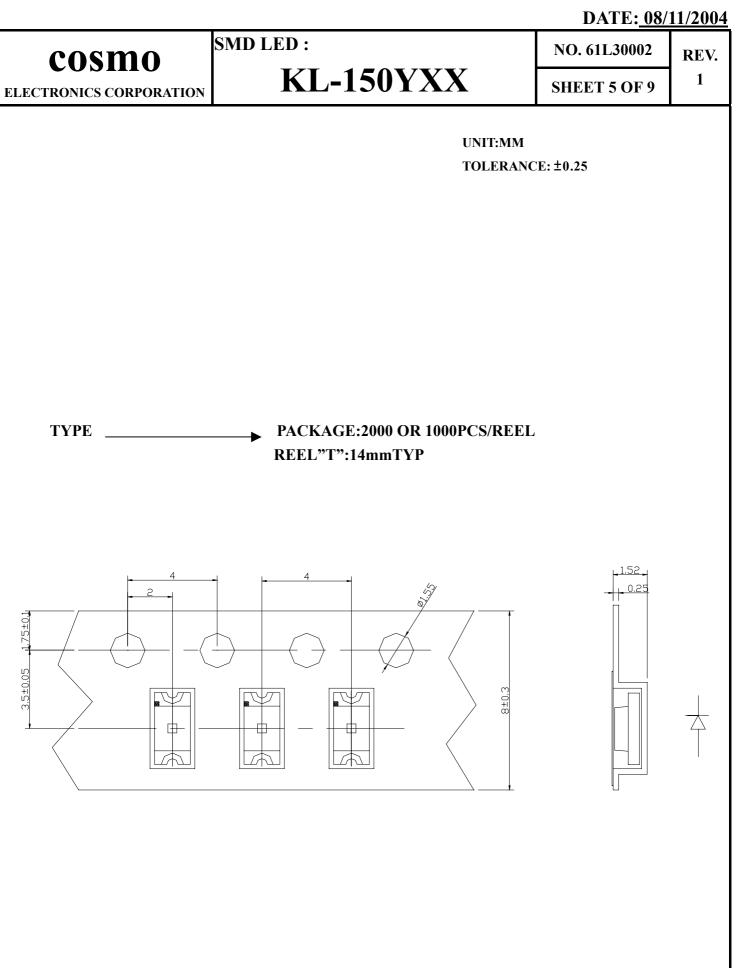
Operating characteristics (TA=25°C)		Y Yellow (GaAsp)	Unit
Forward voltage(typ.) IF=20mA	VF	2.1	V
Forward voltage(max.) IF=20mA	VF	2.5	V
Reverse current(max.) Vr=5V	Ir	10	uA
Wavelength at dominant emission(typ.) IF=20mA	λσ	590	nm
Wavelength at peak emission(typ.)	λ Ρ	589	nm
IF=20mA Spectral line half-width IF=20mA	Δλ	35	nm
IF=20MA Capacitance VF=0V,f=1MHz	С	10	pF

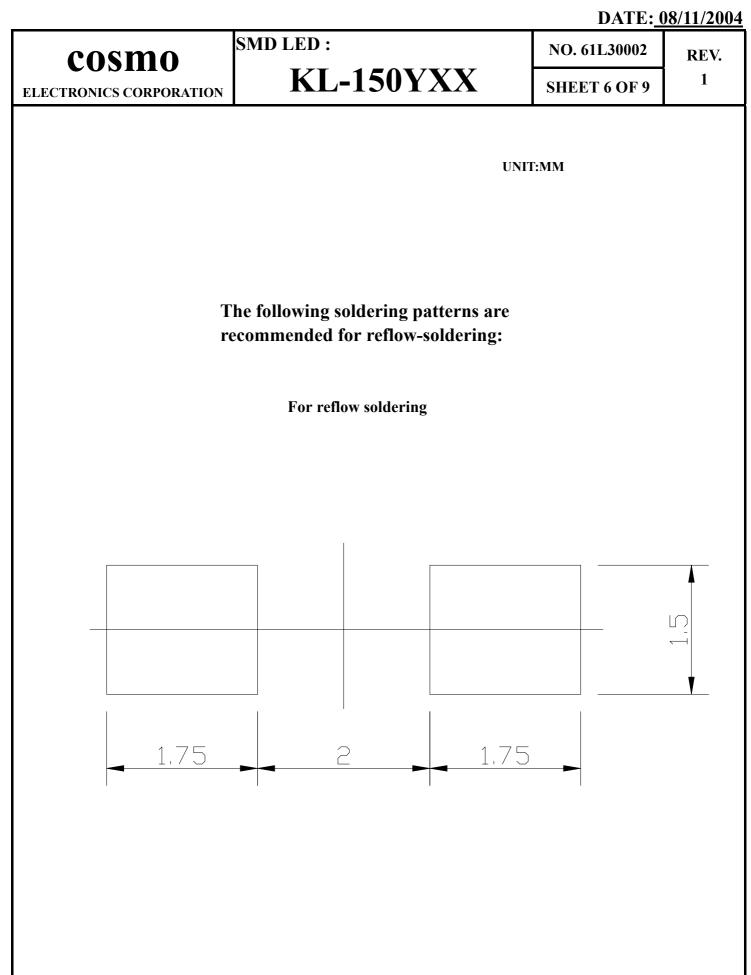


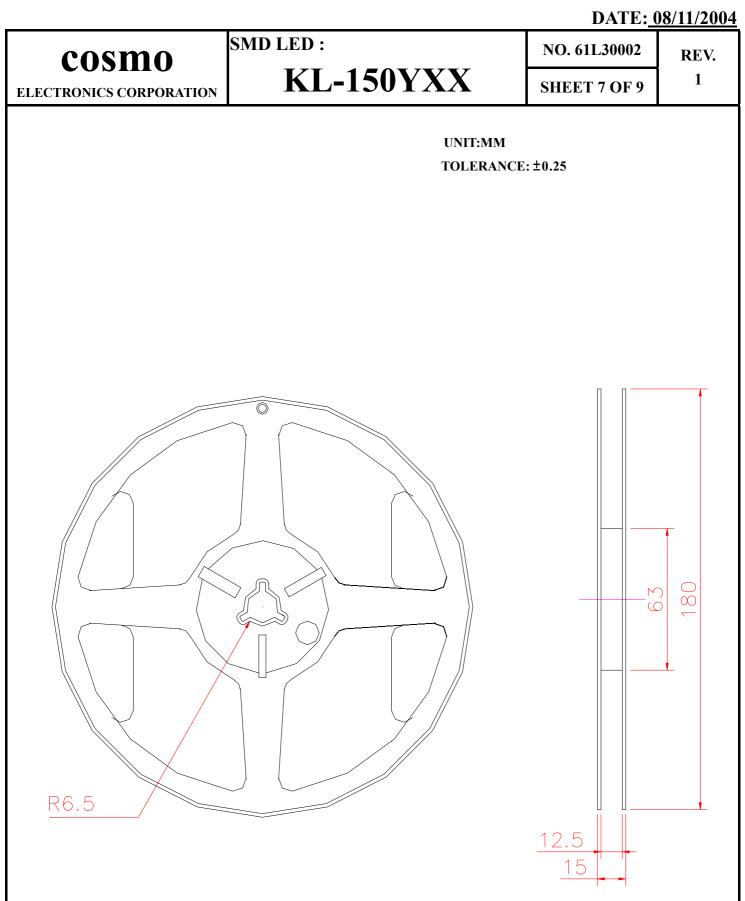
DATE: 08/11/2004



View Angle 2 ∂1/2=120°







#### DATE: 08/11/2004 **SMD LED :** NO. 61L30002 cosmo REV. **KL-150YXX** 1 **SHEET 8 OF 9 ELECTRONICS CORPORATION SOLDERING SMT REFLOW SOLDERING INSTRUCTIONS** 10 sec MAX Temp (°C)TEMPERATURE 230 4° C/sec max 140~160°C - $4^{\circ}$ C/sec max Time 35sec MAX -60~120sec-SOLDERING INSRTUCTIONS **DIP AND WAVE SOLDERING** IRON SOLDERING(WITH 1.5mm IRON TIP) **TYPES TEMPERATURE OF** DISTANCE FROM MAXLMUM DISTANCE FORM **TEMPERATURE OF** MAXLMUM THE SOLDERING SOLDERING SOLDER JOINT SOLDERING SOLDERING SOLDER JOINT BATH TIME **TO CASE** IRON TIME **TO CASE** ≦**260**°C 3S >2mm **≦260**°C 3S >2mm LEDS ≦**260**°C 5S >4mm ≦**260**°C **5**S >4mm DISPLAYS ≤**260**°C >2mm ≤**260**°C >2mm 3S 3S

#### DATE: 08/11/2004

REV.

1

NO. 61L30002

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cosmo

ELECTRONICS CORPORATION

SMD LED :

KL-150YXX

#### **SMD HANDLING AND APPLICATION PRECAUTIONS**

#### STORAGE

(1.1)It is recommended to store the devices in accordance with the following conditions:

Humidity: 60%RH Max.

Temperature:  $5^{\circ}C \sim 30^{\circ}C$  (41°F ~ 86°F)

(1.2)Shelf life in sealed bag: 12 month at  $<5^{\circ}C \sim 30^{\circ}C$  and <30%RH. After the package is opened, the products should be used within 72hrs. Or they should be kept at  $\leq 20\%$ RH in zip -locked sealed bags.

#### DRY PACK AND BAKING

SMD LEDs are MOISTURE SENSITIVE devices. Avoid absorbing moisture at any time during transportation and/or storage. It is recommended to bake before soldering when the pack is unsealed after 72 hrs, or any suspicious moisture being found. Bake devices in accordance with the following conditions:

- (a)  $60\pm3^{\circ}$ C x (12~24hrs) and <5%RH, taped reel type
- (b)  $100\pm3^{\circ}C$  x (45min~1hr), loose packing type, or
- (c)  $130\pm3^{\circ}C$  x (15~30min), loose packing type

#### **ELECTRIC STATIC DISCHARGE(ESD) PROTECTION**

Materials with GaN, InGaN, AlInGaP are STATIC SENSITIVE devices. They will be packed in anti-static bags. ESD protection must be deliberatively observed from the initial design stage. The static -electric discharge may result in severe malfunction of the devices. In the events of manual working in process, make sure the devices are well protected from ESD at any time. Surge before and during handling products.